

Fig. 1: Forward current versus forward voltage at different temperatures (typical values).

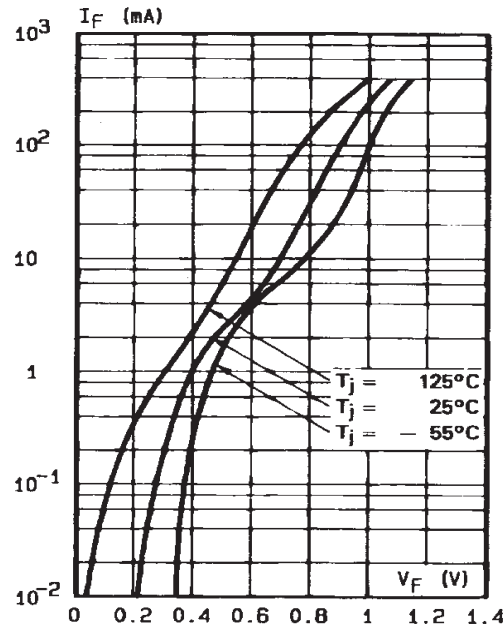


Fig. 2: Forward current versus forward voltage (typical values).

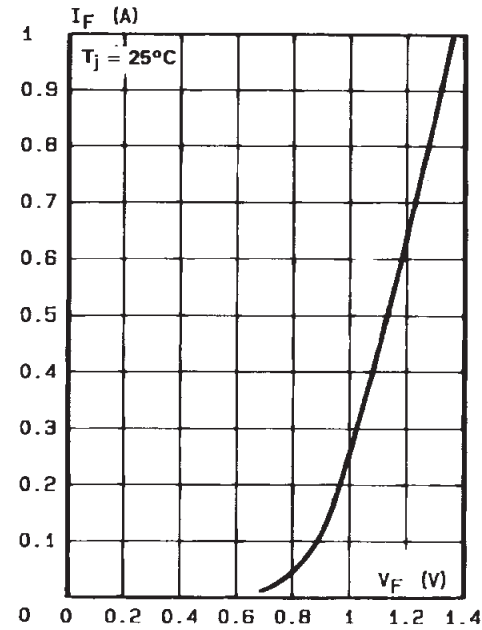


Fig. 3: Reverse current versus junction temperature.

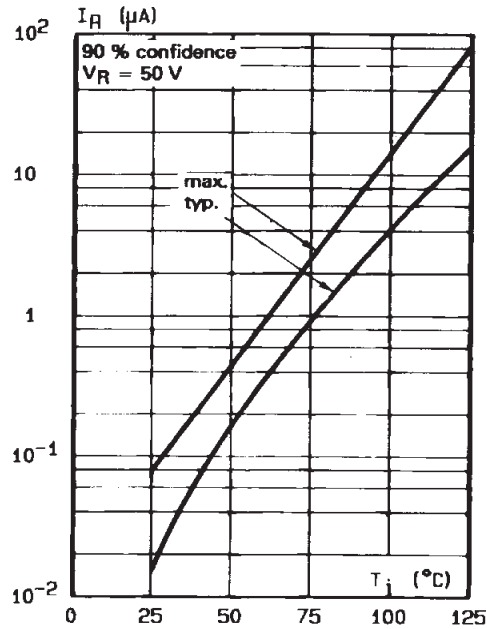


Fig. 4: Reverse current versus continuous reverse voltage (typical values).

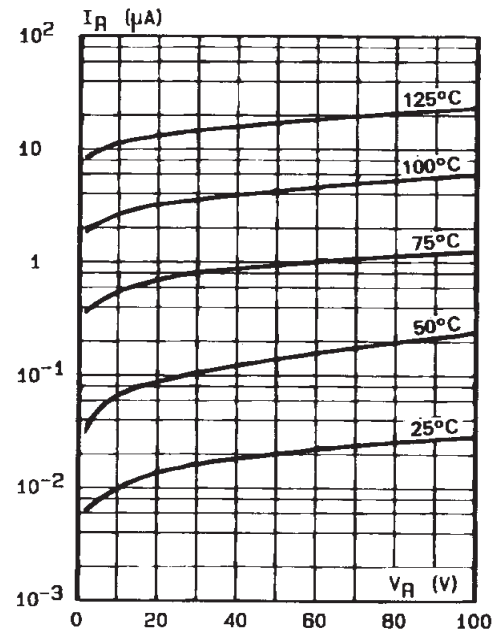
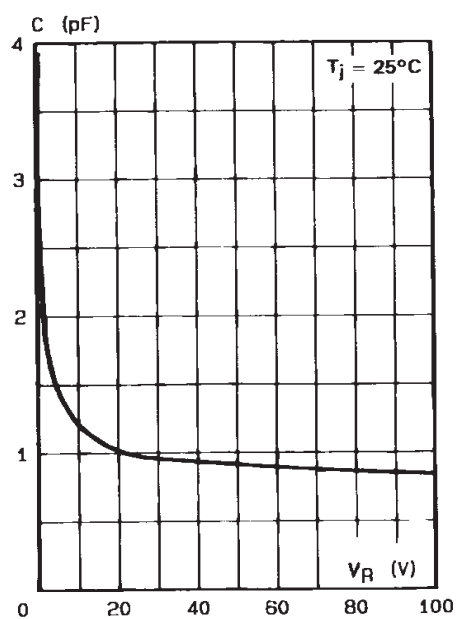
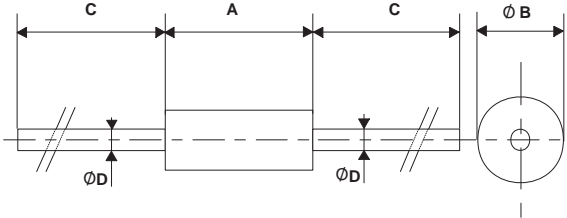


Fig. 5: Capacitance C versus reverse applied voltage V_R (typical values).



PACKAGE MECHANICAL DATA
DO-35

	REF.	DIMENSIONS			
		Millimeters		Inches	
		Min.	Max.	Min.	Max.
	A	3.05	4.50	0.120	0.177
B		1.53	2.00	0.060	0.079
C		28.00		1.102	
D		0.458	0.558	0.018	0.022

Cooling method : by convection and conduction
Marking: clear, ring at cathode end.
Weight: 0.15g

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